

General Description

The MAX14562 protects valuable consumer circuits against voltage faults of up to +36V. This robust protection is implemented in a three-step scheme for a superior result. If the input is below the preset regulated outputvoltage (VPROV) threshold, the output tracks the input minus the voltage drop (RON x ILOAD) across the pass FET. If the input exceeds VPROV, the output is regulated to VPROV. If the input rises further and exceeds the overvoltage lockout cutoff threshold (VOVLO), the output is disconnected from the input.

A low resistance $160m\Omega$ (typ) FET is integrated in the MAX14562, effectively reducing the component count and application footprint. The MAX14562 also features thermal shutdown protection against a short-circuit event.

The MAX14562 is specified over the extended -40°C to +85°C temperature range and is available in 8-pin TDFN (2mm x 2mm) package.

Applications

Digital Cameras Mobile Phones Bluetooth Headset Smartphones

Portable Media Player F-Book

PDAs Mobile Internet Device

Features

- ◆ Input Voltage Protection Up to +36V
- ◆ Preset Regulated Output Voltage (+5.15V typ)
- Integrated 160mΩ (typ) N-Channel MOSFET Switch
- Soft-Start to Minimize In-Rush Current
- Overvoltage Cutoff Protection +8V (typ)
- **♦ Thermal Shutdown Protection**
- → -40°C to +85°C Operating Temperature Range

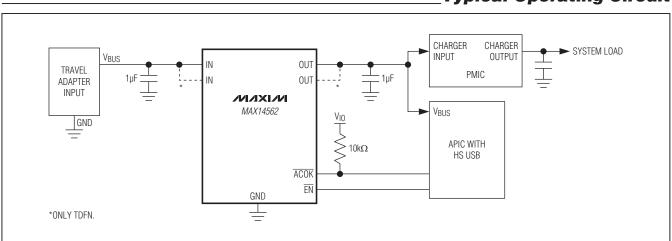
Ordering Information

PART	TEMP	PIN-	TOP
	RANGE	PACKAGE	MARK
MAX14562ETA+T	-40°C to +85°C	8 TDFN-EP*	ADI

+Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

Typical Operating Circuit



^{*}EP = Exposed pad.

ABSOLUTE MAXIMUM RATINGS

(Voltages referenced to GND.)	
IN	0.3V to +40V
OUT	-0.3V to +6V
EN, ACOK	0.3V to +6V
Continuous Current Through IN/OUT	
8-Pin TDFN	±1.6A
10ms Current Through IN/OUT	
8-Pin TDFN	±2A
8-Pin TDFN 10ms Current Through IN/OUT	

Continuous Power Dissipation (T _A = +70°C):	
8-Pin TDFN (derate 11.9mW/°C above +70°C)	953mW
Operating Temperature Range40°	'C to +85°C
Storage Temperature Range65°C	c to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
Soldering Temperature (reflow)	+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

PACKAGE THERMAL CHARACTERISTICS (Note 1)

TDFN

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maxim-ic.com/thermal-tutorial.

ELECTRICAL CHARACTERISTICS

 $(V_{IN} = +2.2V \text{ to } +36V, T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at $V_{IN} = +5.0V \text{ and } T_A = +25^{\circ}\text{C.}$) (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage	VIN			2.2		36	V
		IOUT = 0mA, VI	N = 6.5V	4.85	5.15	5.45	
Preset Regulated Output Voltage	VPROV	IOUT = 200mA,	I _{OUT} = 200mA, V _{IN} = 6.5V		5.15	5.45	V
		IOUT = 800mA,	VIN = 6V (Note 3)	4.75	5.15	5.45	
Output Valtage	Volum		VIN > VPROV		VPROV		V
Output Voltage	Vout	IOUT = 0mA	V _{IN} < V _{PROV} (Note 4)		VIN		V
Overvoltage Lockout Cutoff Threshold Rising	Vovlo	IN rising		7.44	8	8.56	V
Overvoltage Lockout Hysteresis		% of typ VovLo)		1		%
	I _{IN}	$\overline{\text{EN}} = \text{low}, \text{V}_{\text{IN}} = 4.5 \text{V}, \text{IOUT} = 0 \text{mA}$			120	260	
Input Supply Current		EN = low, V _{IN} = 7V, I _{OUT} = 0mA			300	550	- μΑ
Input Shutdown Current	I _{IN_Q}	\overline{EN} = high, V_{IN} = 3V			2.5	5	μΑ
OUT Shutdown Current		$V_{IN} = 5V$, $V_{OUT} = 4V$, $\overline{EN} = high$		-1		+1	μΑ
On-Resistance	Ron	V _{IN} = 4.75V, I _{OUT} = 100mA				280	mΩ
LDO Load Capacitance		IOUT up to 0.8A			10		μF
DIGITAL SIGNALS (EN, ACOK)							
EN Input High Voltage	VIH			1.4			V
EN Input Low Voltage	VIL					0.4	V
EN Input Leakage Current	ILEAK	VEN = 0V or 5.5V		-150		+150	nA
ACOK Output Low Voltage	VoL	V _{IO} = 3.3V, I _{SINK} = 1mA (see <i>Typical Operating Circuit</i>)				0.4	V
ACOK Leakage Current		V _{IO} = 3.3V, ACOK deasserted (see <i>Typical Operating Circuit</i>)		-200		+200	nA

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = +2.2V \text{ to } +36V, T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at $V_{IN} = +5.0V \text{ and } T_A = +25^{\circ}\text{C}.)$ (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
TIMING CHARACTERISTICS (Note 4)							
Input Debounce Time	tDEB	VIN_MIN < VIN < VOVLO until charge pump turns on, see Figure 1	10	20	35	ms	
ACOK Time	tACOK	VIN_MIN < VIN < VOVLO to ACOK low until charge pump turns on, see Figure 1	20	40	70	ms	
Turn-on Time During Soft-Start	ton	RLOAD = 100Ω , CLOAD = 1μ F, VOUT = 20% of V _{IN} to 80% of V _{IN} , see Figure 1		48		μs	
Overvoltage Turn-Off Time	toff	$V_{IN} > V_{OVLO}$ to $V_{OUT} = 80\%$ of V_{PROV} , $R_{LOAD} = 100\Omega$, see Figure 1		1		μs	
THERMAL PROTECTION							
Thermal Shutdown	TSHDN			150		°C	
Thermal Hysteresis	THYST			20		°C	

Note 2: All devices are 100% production tested at $T_A = +25$ °C. Limits over the operating temperature range are guaranteed by design and not production tested.

Note 3: Thermally limited, guaranteed by design, and not production tested.

Note 4: In linear mode, as IOUT increases, the OUT voltage drops due to a voltage across Q1 (see Functional Diagram).

Note 5: All timing characteristics are measured using 20% and 80% levels unless otherwise specified.

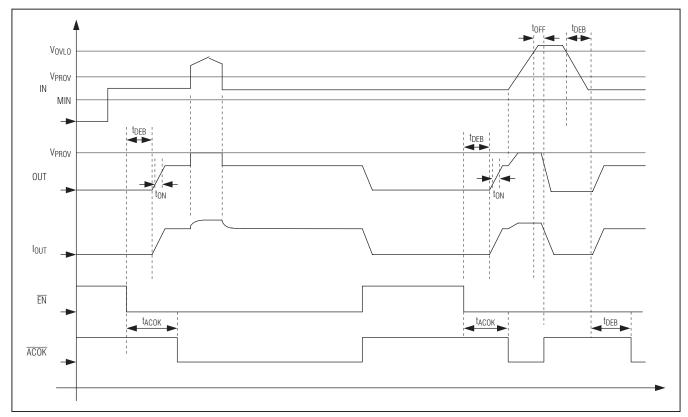
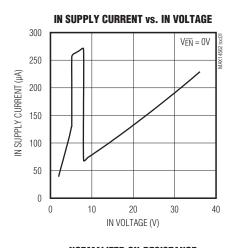
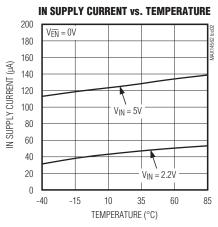


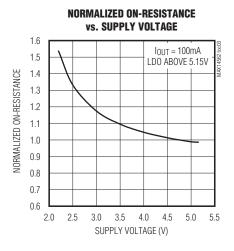
Figure 1. Enable/Select Time

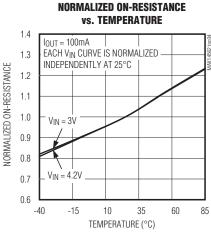
Typical Operating Characteristics

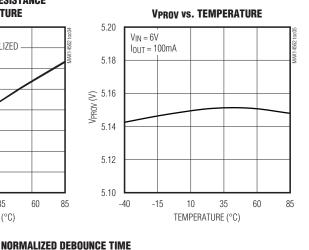
 $(C_{IN} = 1\mu F, C_{OUT} = 4.7\mu F, T_A = +25^{\circ}C, unless otherwise noted.)$

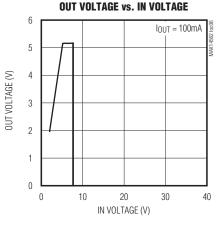




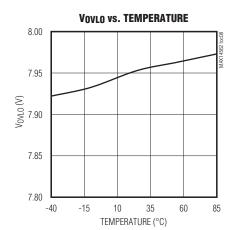






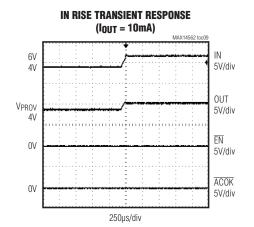


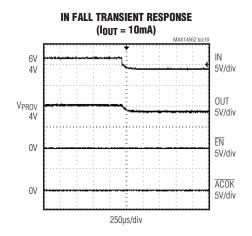
vs. TEMPERATURE 1.20 $V_{IN} = 5V$ 1.15 $I_{OUT} = 100 mA$ NORMALIZED DEBOUNCE TIME 1.10 1.05 1.00 0.95 0.90 0.85 0.80 -40 -15 35 60 85 TEMPERATURE (°C)

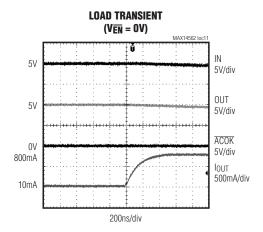


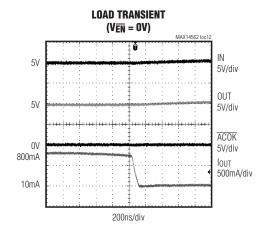
Typical Operating Characteristics (continued)

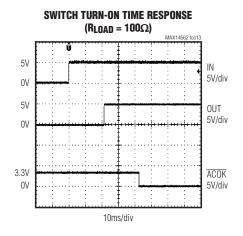
 $(C_{IN} = 1\mu F, C_{OUT} = 4.7\mu F, T_A = +25^{\circ}C, unless otherwise noted.)$

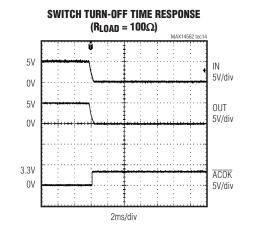






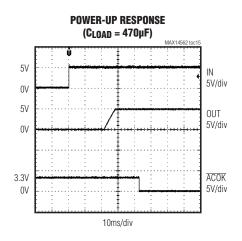


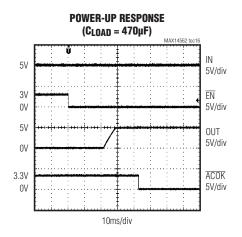




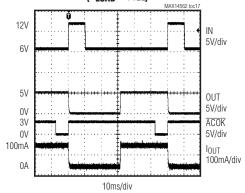
Typical Operating Characteristics (continued)

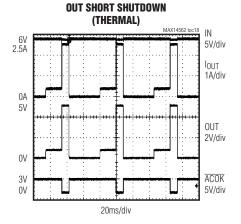
(CIN = 1μ F, COUT = 4.7μ F, TA = $+25^{\circ}$ C, unless otherwise noted.)



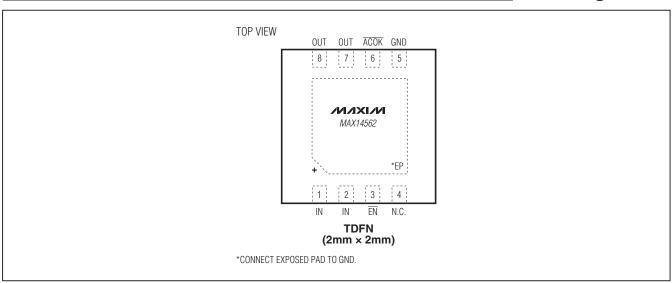








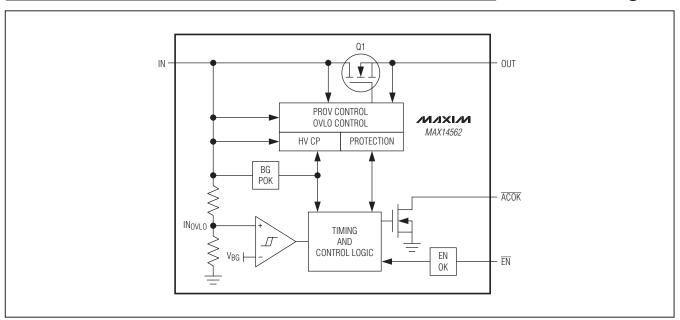
Pin Configuration



Pin Description

PIN	NAME	FUNCTION
1,2	IN	Overvoltage Protection Input. Bypass IN with a 1µF ceramic capacitor to get ±15kV HBM ESD protection. No capacitor is required for ±2kV HBM ESD protection. Externally connect both IN pins together.
3	EN	Active-Low Enable Input. Drive $\overline{\text{EN}}$ low to turn on the device. Drive $\overline{\text{EN}}$ high to turn off the device.
4	N.C.	No Connection. Not internally connected.
5	GND	Ground
6	ACOK	Open-Drain Flag Output. \overline{ACOK} is driven low after input voltage is stable between minimum V_{IN} and V_{OVLO} after soft-start time (double of debounce time). Connect a pullup resistor from \overline{ACOK} to the logic I/O voltage of the host system.
7,8	OUT	Overvoltage Protection Output. Bypass OUT with a 1µF or larger ceramic capacitor (see Table 1). Externally connect both OUT pins together.
_	EP	Exposed Pad. Connect EP to GND.

Functional Diagram



Detailed Description

The MAX14562 features the overvoltage protection to the charger input VBUS line when a travel adapter (TA) is used. In addition, the MAX14562 features a low 160m Ω (typ) on-resistance internal FET (Q1) and protects the low-voltage system against voltage faults up to +36V.

The MAX14562 features three-step overvoltage protection. When the input is below the preset regulated output-voltage (VPROV) threshold, the output follows the input minus the voltage drop across the pass FET (RON x ILOAD). When the input exceeds VPROV, the output is regulated to VPROV. If the input rises further and exceeds the overvoltage lockout cutoff (VOVLO) threshold, the output is disconnected from the input. The MAX14562 also features thermal shutdown protection against short-circuit events.

Soft-Start

To minimize inrush current, the MAX14562 features a soft-start capability to slowly turn on Q1.

Soft-start function permits the device to charge the load capacitor up to $1000\mu F$ by controlled current. The soft-start is initiated when the debounce time ends (OUT

starts charging) and ends when $\overline{\text{ACOK}}$ is asserted low, 15ms (typ).

Linear Mode

When the input voltage exceeds the minimum IN voltage but is below VPROV, OUT follows IN with a minimum voltage drop (RON x ILOAD) across pass FET after the debounce time, tDEB, and \overline{ACOK} is asserted.

The LDO mode needs a capacitor on OUT. The recommended value is $10\mu F$ for load currents up to 800mA (Table 1).

Preset Regulated Output-Voltage Mode (PROV)

When IN goes above the preset regulated output voltage (VPROV), Q1 provides a constant voltage of VPROV at OUT, and \overline{ACOK} is asserted.

Table 1. Recommended Load Capacitance

	•
LOAD CURRENT (mA)	LOAD CAP (μF)
10	1
50	2.2
100	4.7
800	10

Overvoltage Lockout Mode (OVLO)

When IN goes above the overvoltage lockout threshold (VovLO), OUT is disconnected from IN and \overline{ACOK} is deasserted. Power dissipation increases when the input goes higher than VPROV. The overvoltage lockout threshold is set to further the power dissipation. When IN drops below VovLO, the debounce time starts counting. After the debounce time (2 x tDEB), OUT follows IN again and \overline{ACOK} is asserted.

Thermal Shutdown

The MAX14562 features a thermal shutdown function necessary to protect the device. The device turns off and \overline{ACOK} is deasserted when the junction temperature exceeds +150°C (typ). When the temperature drops 20°C (typ) below 150°C (typ), the device turns back on and Q1 is turned on after the debounce time.

_Applications Information

Power-Supply Decoupling

Bypass IN pin(s) to ground with a $1\mu F$ or larger ceramic capacitor placed as close as possible to the device.

Chip Information

PROCESS: BICMOS

Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTPUT	LAND
TYPE	CODE	NO.	PATTERN NO.
8 TDFN-EP	T822+1	21-0168	90-0064

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	9/10	Initial release	_
1	8/11	Removed SC70 pin information from data sheet. Added additional conditions to Preset Regulated Output Voltage parameter in the <i>Electrical Characteristics</i> table	1, 2, 3, 7, 9

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